

ABSTRACT

Method and apparatus for cutting a multi-layer substrate by dual laser irradiation.

- 5 A method and apparatus are provided for cutting a substrate using dual laser irradiation. Two lasers are provided, one focussed on a first substrate layer and one on a second layer so as to ablate the said layers. The wavelength and other parameters of the lasers are selected so as to correspond with the layer material to be ablated.
- 10 The invention is particularly suitable for the singulation of IC packages.

(Figure 5)

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